/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak pulse power (t_p = 8/20μs)	P_K	69	W
Peak pulse current (t_p = 8/20μs)	I_{PP}	5.5	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	T_J	150	
Storage temperature	T_{STG}	-55~+150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	V_{RWM}				3.3	V
Reverse leakage current	I_R	V_{RWM} =3.3V			0.1	uA
Reverse breakdown voltage[1)]	V_{BR}	I_T = 1mA	5.0		6.8	V
Clamping voltage [2)]	V_C	I_{PP} = 1A t_p = 8/20μs			9.8	V
		I_{PP} = 5.5A t_p = 8/20μs			12.5	V
Junction capacitance	C_J	V_R = 0V f = 1MHz			15	pF

Notes:

1) V_{BR} is measured with a pulse test current IT at an ambient temperature of 25 .

2) Non-repetitive current pulse, according to IEC61000-4-5.

/ Electrical Characteristic Curve

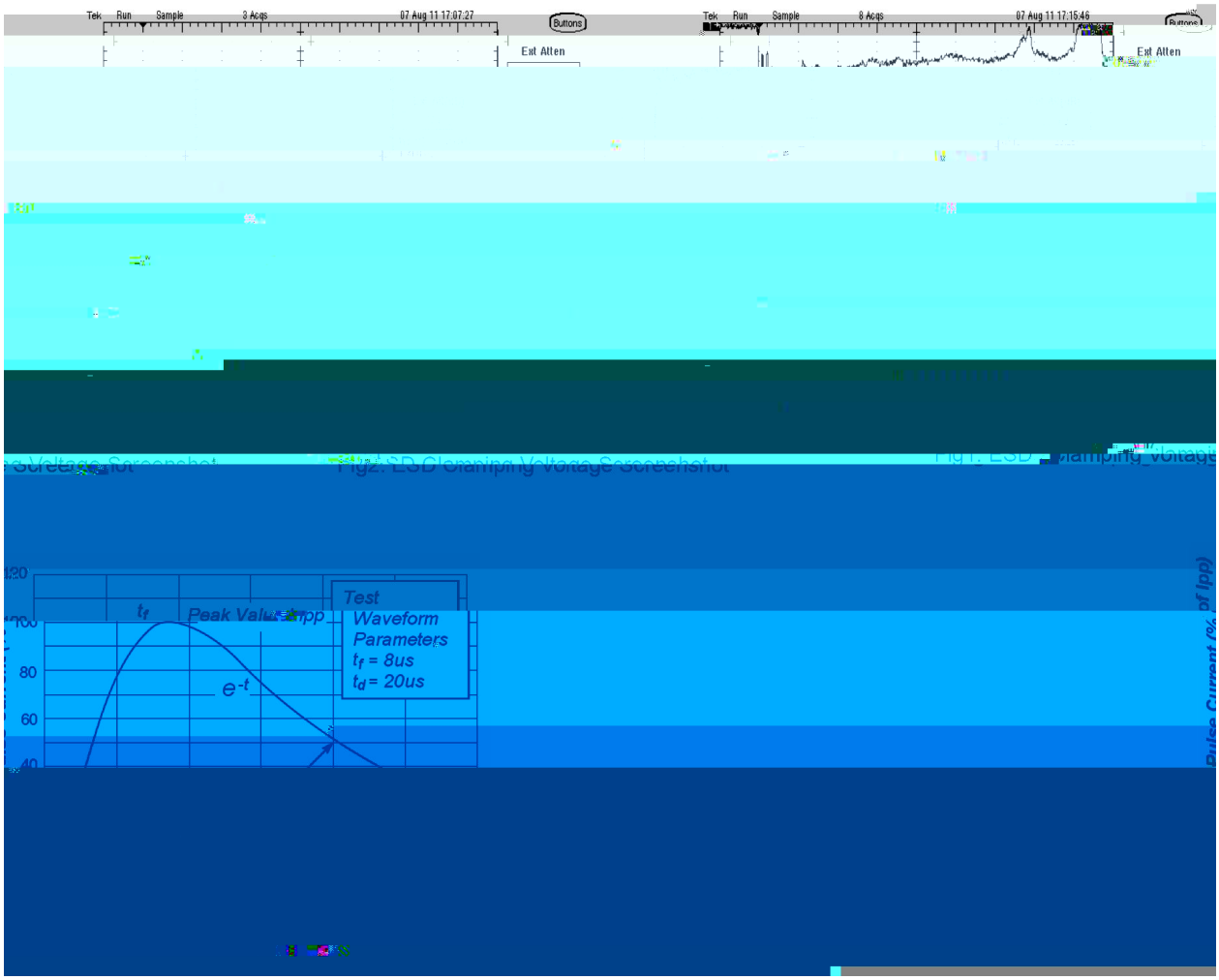
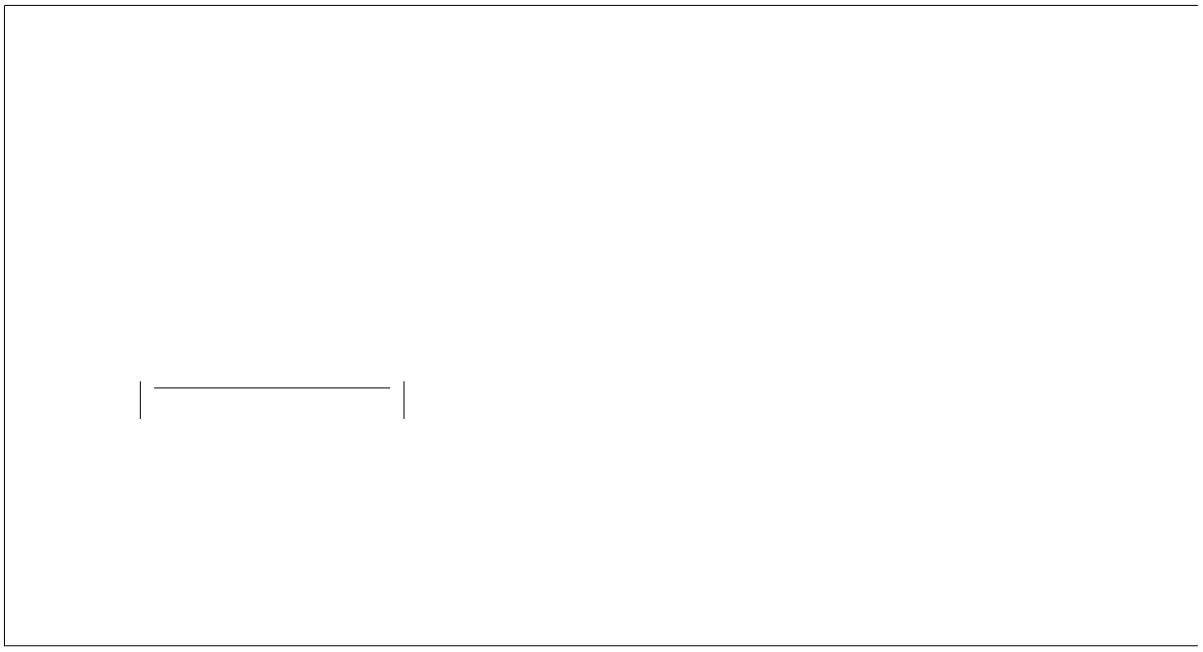


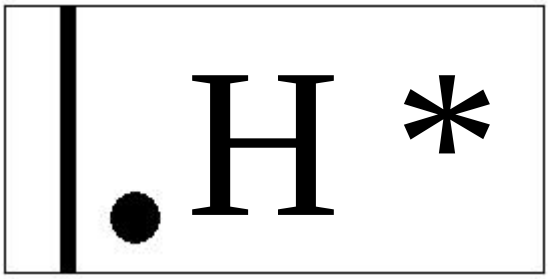
Fig2. ESD Clamping Voltage Screenshot

/ Package Dimensions

DFN0603 Unit:mm



/ Marking Instructions



Note

H	Product Type
*	Lot No. Code,code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

605 5